

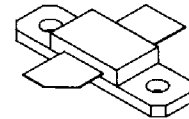
**The RF MOSFET Line**  
**RF Power Field Effect Transistors**  
**N-Channel Enhancement-Mode Lateral MOSFETs**

**MRF21010LR1**  
**MRF21010LSR1**

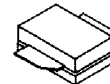
Designed for W-CDMA base station applications with frequencies from 2110 to 2170 MHz. Suitable for FM, TDMA, CDMA and multicarrier amplifier applications. To be used in Class AB for PCN-PCS/cellular radio and WLL applications.

- Typical W-CDMA Performance: -45 dBc ACPR, 2140 MHz, 28 Volts, 5 MHz Offset/4.096 MHz BW, 15 DTCH  
Output Power — 2.1 Watts  
Power Gain — 13.5 dB  
Efficiency — 21%
- High Gain, High Efficiency and High Linearity
- Integrated ESD Protection
- Designed for Maximum Gain and Insertion Phase Flatness
- Capable of Handling 10:1 VSWR @ 28 Vdc, 2170 MHz, 10 Watts CW Output Power
- Excellent Thermal Stability
- Characterized with Series Equivalent Large-Signal Impedance Parameters
- In Tape and Reel. R1 Suffix = 500 Units per 32 mm, 13 Inch Reel.
- Low Gold Plating Thickness on Leads. L Suffix Indicates 40 $\mu$ m Nominal.

**2170 MHz, 10 W, 28 V**  
**LATERAL N-CHANNEL**  
**BROADBAND**  
**RF POWER MOSFETs**



**CASE 360B-05,**  
**NI-360**  
**MRF21010LR1**



**CASE 360C-05,**  
**NI-360S**  
**MRF21010LSR1**

**MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Drain-Source Voltage	V <sub>DSS</sub>	65	Vdc
Gate-Source Voltage	V <sub>GS</sub>	- 0.5, +15	Vdc
Total Device Dissipation @ T <sub>C</sub> = 25°C Derate above 25°C	P <sub>D</sub>	43.75 0.25	W W/°C
Storage Temperature Range	T <sub>stg</sub>	- 65 to +150	°C
Operating Junction Temperature	T <sub>J</sub>	200	°C

**THERMAL CHARACTERISTICS**

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction to Case	R <sub><math>\theta</math>JC</sub>	5.5	°C/W

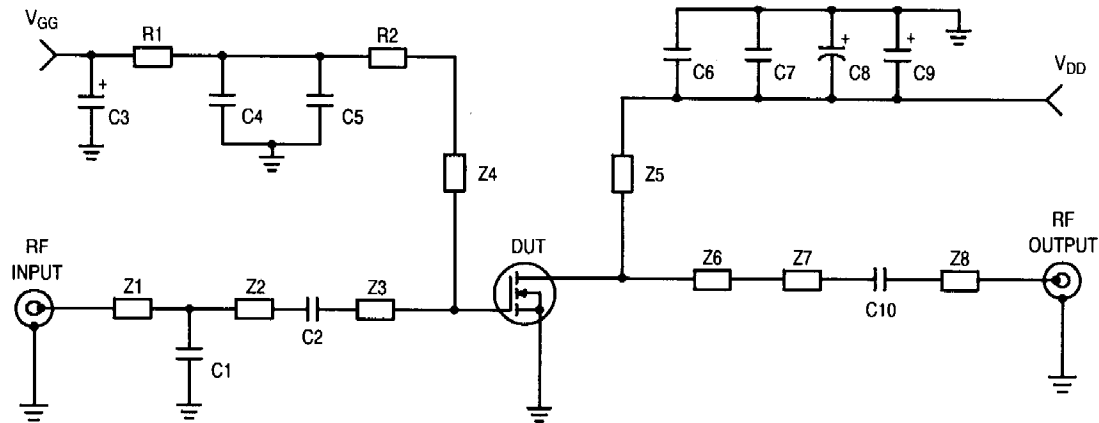
**ESD PROTECTION CHARACTERISTICS**

Test Conditions	Class
Human Body Model	1 (Minimum)
Machine Model	M1 (Minimum)

NOTE - **CAUTION** - MOS devices are susceptible to damage from electrostatic charge. Reasonable precautions in handling and packaging MOS devices should be observed.



# Freescale Semiconductor, Inc.



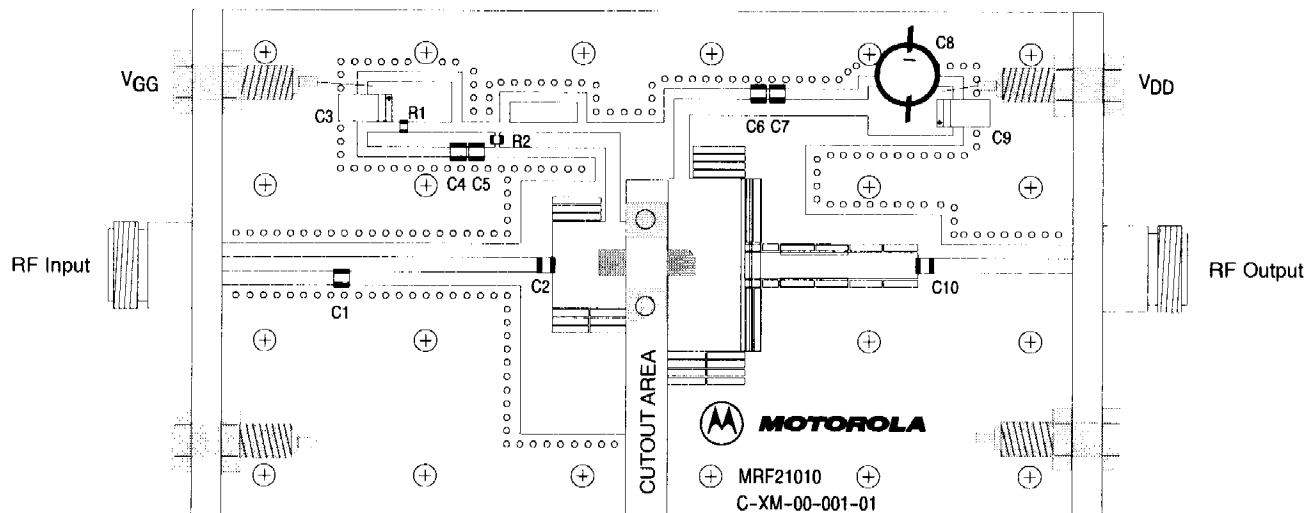
Z1	0.964" x 0.087" Microstrip	Z6	0.453" x 1.118" Microstrip
Z2	0.905" x 0.087" Microstrip	Z7	0.921" x 0.154" Microstrip
Z3	0.433" x 0.512" Microstrip	Z8	0.925" x 0.087" Microstrip
Z4	1.068" x 0.087" Microstrip	PCB	Taconic TLX8-0300, 0.030", $\epsilon_r = 2.55$
Z5	0.752" x 0.087" Microstrip		

**Figure 1. MRF21010L Test Circuit Schematic**

**Table 1. MRF21010L Test Circuit Component Designations and Values**

Part	Description	Value, P/N or DWG	Manufacturer
C1 *	2.2 pF Chip Capacitor, B Case	100B2R2BW	ATC
	(eared)		
	(earless)	100B1R8BW	ATC
C2	0.5 pF Chip Capacitor, B Case	100B0R5BW	ATC
C3, C9	10 $\mu$ F, 35 V Tantalum Chip Capacitors	293D106X9035D2T	Sprague - Vishay
C4, C7	1 nF Chip Capacitors, B Case	100B102JW	ATC
C5, C6	5.6 pF Chip Capacitors, B Case	100B5R6BW	ATC
C8	470 $\mu$ F, 63 V Electrolytic Capacitor		
C10	10 pF Chip Capacitor, B Case	100B100GW	ATC
N1, N2	Type N Connector Flange Mounts	3052-1648-10	Macom
R1	1.0 k $\Omega$ Chip Resistor (0805)		
R2	12 $\Omega$ Chip Resistor (0805)		

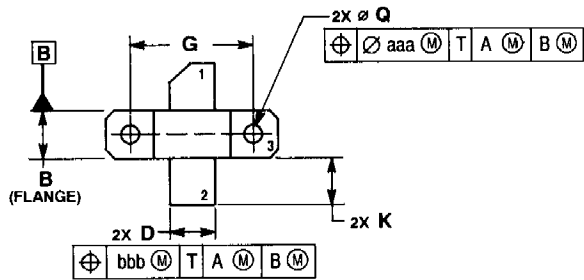
\* Piece part depending on eared / earless version of the device.



**Figure 2. MRF21010L Test Circuit Component Layout**

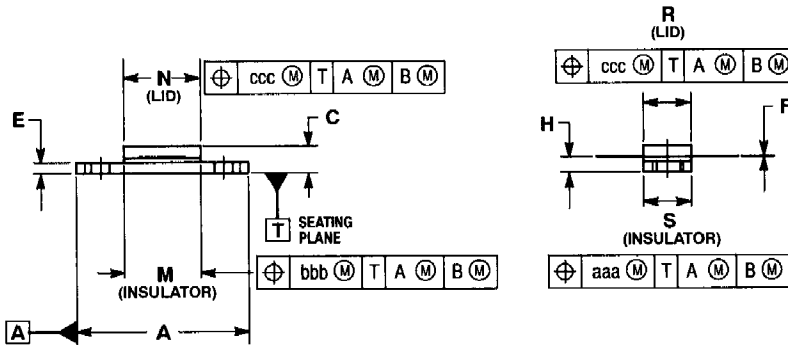
**ELECTRICAL CHARACTERISTICS** ( $T_C = 25^\circ\text{C}$  unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
<b>OFF CHARACTERISTICS</b>					
Drain-Source Breakdown Voltage ( $V_{GS} = 0\text{ Vdc}$ , $I_D = 10\ \mu\text{A}$ )	$V_{(BR)DSS}$	65	—	—	Vdc
Zero Gate Voltage Drain Current ( $V_{DS} = 28\text{ Vdc}$ , $V_{GS} = 0\text{ Vdc}$ )	$I_{DSS}$	—	—	10	$\mu\text{Adc}$
Gate-Source Leakage Current ( $V_{GS} = 5\text{ Vdc}$ , $V_{DS} = 0\text{ Vdc}$ )	$I_{GSS}$	—	—	1	$\mu\text{Adc}$
<b>ON CHARACTERISTICS</b>					
Gate Threshold Voltage ( $V_{DS} = 10\text{ V}$ , $I_D = 50\ \mu\text{A}$ )	$V_{GS(th)}$	2.5	3	4	Vdc
Gate Quiescent Voltage ( $V_{DS} = 28\text{ V}$ , $I_D = 100\text{ mA}$ )	$V_{GS(Q)}$	2.5	4	4.5	Vdc
Drain-Source On-Voltage ( $V_{GS} = 10\text{ V}$ , $I_D = 0.5\text{ A}$ )	$V_{DS(on)}$	—	0.4	0.5	Vdc
Forward Transconductance ( $V_{DS} = 10\text{ V}$ , $I_D = 1\text{ A}$ )	$g_{fs}$	—	0.95	—	S
<b>DYNAMIC CHARACTERISTICS</b>					
Reverse Transfer Capacitance ( $V_{DS} = 28\text{ Vdc}$ , $V_{GS} = 0$ , $f = 1\text{ MHz}$ )	$C_{rss}$	—	1	—	pF
<b>FUNCTIONAL TESTS</b> (In Motorola Test Fixture, 50 ohm system)					
Two-Tone Common Source Amplifier Power Gain ( $V_{DD} = 28\text{ Vdc}$ , $P_{out} = 10\text{ W PEP}$ , $I_{DQ} = 100\text{ mA}$ , $f_1 = 2110\text{ MHz}$ , $f_2 = 2170\text{ MHz}$ , Tone Spacing = 100 KHz)	$G_{ps}$	12	13.5	—	dB
Two-Tone Drain Efficiency ( $V_{DD} = 28\text{ Vdc}$ , $P_{out} = 10\text{ W PEP}$ , $I_{DQ} = 100\text{ mA}$ , $f_1 = 2110\text{ MHz}$ , $f_2 = 2170\text{ MHz}$ , Tone Spacing = 100 KHz)	$\eta$	31	35	—	%
Third Order Intermodulation Distortion ( $V_{DD} = 28\text{ Vdc}$ , $P_{out} = 10\text{ W PEP}$ , $I_{DQ} = 100\text{ mA}$ , $f_1 = 2110\text{ MHz}$ , $f_2 = 2170\text{ MHz}$ , Tone Spacing = 100 KHz)	IMD	—	-35	-30	dBc
Input Return Loss ( $V_{DD} = 28\text{ Vdc}$ , $P_{out} = 10\text{ W PEP}$ , $I_{DQ} = 100\text{ mA}$ , $f_1 = 2110\text{ MHz}$ , $f_2 = 2170\text{ MHz}$ , Tone Spacing = 100 KHz)	IRL	—	-12	-10	dB
Output Power, 1 dB Compression Point, CW ( $V_{DD} = 28\text{ Vdc}$ , $I_{DQ} = 100\text{ mA}$ , $f = 2170\text{ MHz}$ )	P1dB	—	11	—	W
Common-Source Amplifier Power Gain ( $V_{DD} = 28\text{ Vdc}$ , $P_{out} = 10\text{ W CW}$ , $I_{DQ} = 100\text{ mA}$ , $f = 2170\text{ MHz}$ )	$G_{ps}$	—	12	—	dB
Drain Efficiency ( $V_{DD} = 28\text{ Vdc}$ , $P_{out} = 10\text{ W CW}$ , $I_{DQ} = 100\text{ mA}$ , $f = 2170\text{ MHz}$ )	$\eta$	—	42	—	%
Output Mismatch Stress ( $V_{DD} = 28\text{ Vdc}$ , $P_{out} = 10\text{ W CW}$ , $I_{DQ} = 100\text{ mA}$ , $f = 2170\text{ MHz}$ , VSWR = 10:1, All Phase Angles at Frequency of Tests)	$\Psi$	No Degradation In Output Power Before and After Test			



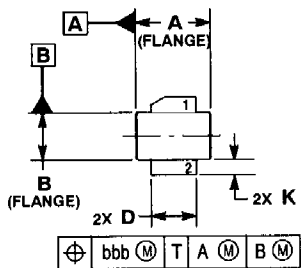
- NOTES:
1. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
  2. CONTROLLING DIMENSION: INCH.
  3. DIMENSION H IS MEASURED 0.030 (0.762) AWAY FROM PACKAGE BODY.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.795	0.805	20.19	20.45
B	0.225	0.235	5.72	5.97
C	0.125	0.175	3.18	4.45
D	0.210	0.220	5.33	5.59
E	0.055	0.065	1.40	1.65
F	0.004	0.006	0.10	0.15
G	0.562	BSC	14.28	BSC
H	0.077	0.087	1.96	2.21
K	0.220	0.250	5.59	6.35
M	0.355	0.365	9.02	9.27
N	0.357	0.363	9.07	9.22
Q	0.125	0.135	3.18	3.43
R	0.227	0.233	5.77	5.92
S	0.225	0.235	5.72	5.97
aaa	0.005	REF	0.13	REF
bbb	0.010	REF	0.25	REF
ccc	0.015	REF	0.38	REF



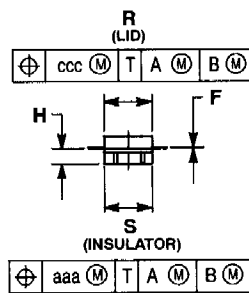
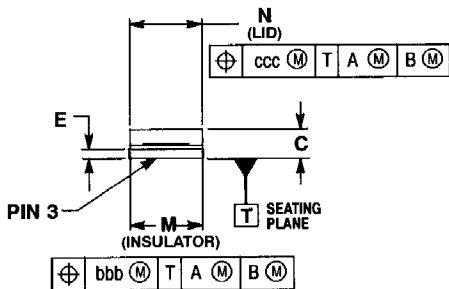
- STYLE 1:  
 PIN 1. DRAIN  
 2. GATE  
 3. SOURCE

**CASE 360B-05  
 ISSUE F  
 NI-360  
 MRF21010LR1**



- NOTES:
1. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
  2. CONTROLLING DIMENSION: INCH.
  3. DIMENSION H IS MEASURED 0.030 (0.762) AWAY FROM PACKAGE BODY.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.375	0.385	9.53	9.78
B	0.225	0.235	5.72	5.97
C	0.105	0.155	2.67	3.94
D	0.210	0.220	5.33	5.59
E	0.035	0.045	0.89	1.14
F	0.004	0.006	0.10	0.15
H	0.057	0.067	1.45	1.70
K	0.085	0.115	2.16	2.92
M	0.355	0.365	9.02	9.27
N	0.357	0.363	9.07	9.22
R	0.227	0.23	5.77	5.92
S	0.225	0.235	5.72	5.97
aaa	0.005	REF	0.13	REF
bbb	0.010	REF	0.25	REF
ccc	0.015	REF	0.38	REF



- STYLE 1:  
 PIN 1. DRAIN  
 2. GATE  
 3. SOURCE

**360C-05  
 ISSUE D  
 NI-360S  
 MRF21010LSR1**